

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Akram et al.

Patent No.: 6,979,895 B2

Issued: December 27, 2005

For: SEMICONDUCTOR ASSEMBLY OF
STACKED SUBSTRATES AND
MULTIPLE SEMICONDUCTOR DICE

Attorney Docket No.: 2269-2809.6US

VIA ELECTRONIC FILING
September 13, 2007

**LETTER MAKING ERRORS OF RECORD
OF PATENT OFFICE MISTAKES (37 C.F.R. § 1.322)**

Attn.: Certificate of Corrections Branch
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

It is noted that several errors appear in this patent of a typographical nature. These errors are due to mistakes in printing on the part of the U.S. Patent and Trademark Office, and occurred through no fault of the Applicants. Please make the following errors of record in the file history of the above-referenced Letters Patent.

IN THE SPECIFICATION:

COLUMN 1, LINE 47, change “flip-chip . The” to --flip-chip. The--

COLUMN 4, LINE 21, change “flip-chip s that are” to --flip-chips that are--

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Respectfully submitted,



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